



## [ThB2] Etch Process Monitoring

<b>Session Date</b>	November 13 (Thu.), 2025
<b>Session Time</b>	10:50-11:50
<b>Session Room</b>	Room B (Grand Ballroom 1, 2F)
<b>Session Chair</b>	Prof. Taewook Nam (Sejong Univ., Korea)

### [ThB2-1]

10:50-11:05

#### Endpoint Detection of Plasma Etching in Small Open Area based on Feature Extraction and Trend Identification

Zimeng Wang (Eindhoven Univ. of Tech., The Netherlands), Jaehyun Kim, Sanghee Han (Sungkyunkwan Univ., Korea), Alp Akçay (Northeastern Univ., USA), Heeyeop Chae (Sungkyunkwan Univ., Korea), and Juseong Lee (Eindhoven Univ. of Tech., The Netherlands)

### [ThB2-2]

11:05-11:20

#### Quantitative Analysis of Radical Species in a Plasma Chamber Using RGA-Based Global Modeling

Seonghyeon Seo, Wonnyoung Jeong (Chungnam Nat'l Univ., Korea), Sijun Kim (LPP-CNRS, France), Youngseok Lee (Tokyo Electron Korea Ltd., Korea), Chulhee Cho, Inho Seong, Minsu Choi, Byeongyeop Choi, Woobeen Lee, Isak Lee, Dongki Lee, Wonkyun Park, Jinhyuk Jang, and Shinjae You (Chungnam Nat'l Univ., Korea)

### [ThB2-3]

11:20-11:35

#### On-Wafer Type Wireless Temperature Sensor for Cryogenic Etch Temperature Monitoring

Kwan Jae Lee (Myongji Univ. and Fine Semitech Corp., Korea), Jae-Hwan Kim, Jaewon Oh (Fine Semitech Corp., Korea), and Sang Jeen Hong (Myongji Univ., Korea)

### [ThB2-4]

11:35-11:50

#### Fault Detection in Plasma Processes Using Optical Emission Spectroscopy with Recurrent Neural Networks-Based Autoencoder

Jaehyeon Kim, Eunchong Park, and Heeyeop Chae (Sungkyunkwan Univ., Korea)